

**FY March 2015
Business Strategy Meeting**

**December 8, 2014
TDK Corporation**



President and CEO Takehiro Kamigama

**General Manager of Humidifier Countermeasures HQ, and
General Manager of Technology HQ**



Executive Vice President Atsuo Kobayashi

**In charge of Applied Film Business Division, Flash Memory Applied Devices
Business Division, EMC & RF Engineering Business Division,
General Manager of Magnet Products Business Group, General Manager of
Power Systems Business Group**



Executive Vice President Hiroyuki Uemura

**TDK-EPC President & CEO
General Manger of Ceramic Capacitors Business Group**



Senior Vice President
Seiji Osaka
TDK-EPC SEVP* & COO



Senior Vice President
Robin Zeng
General Manager of Energy Devices
Business Group



Senior Vice President
Shinya Yoshihara
General Manager of Manufacturing HQ,
General Manager of New Business
Promotion Office of Manufacturing HQ and
Deputy General Manager of Humidifier
Countermeasures HQ



Corporate Officer
Takakazu Momozuka
In charge of Finance & Accounting and
BPR Project



Senior Vice President
Jyuji Yoneyama
In charge of Corporate Systems Reformation,
Human Resources, General Affairs, Legal,
CSR Promotion



Corporate Officer
Shigenao Ishiguro
General Manager of Data Storage &
Thin Film Technology Components
Business Group



Senior Vice President
Noboru Saito
General Manager of Electronic Components
Sales & Marketing Group, and General
Manager of ICT Group of Electronic
Components Sales & Marketing Group

*SEVP : Senior Executive Vice President

◆ Presentation (10:00 - 11:15)

1. Priority Markets and Strategic Products

Senior Vice President Noboru Saito

2. Strategy of Priority Five Businesses

- Inductive Devices, High Frequency Components,
Piezoelectric Material Products

Executive Vice President Hiroyuki Uemura

- Rechargeable Batteries

Senior Vice President Robin Zeng

- HDD Heads

Corporate Office Shigenao Ishiguro

3. Enhancing Financial Strength

Corporate Office Takakazu Momozuka

4. New Development Areas / Summary

President and CEO Takehiro Kamigama

◆Q&A (11:15 - 11:35)

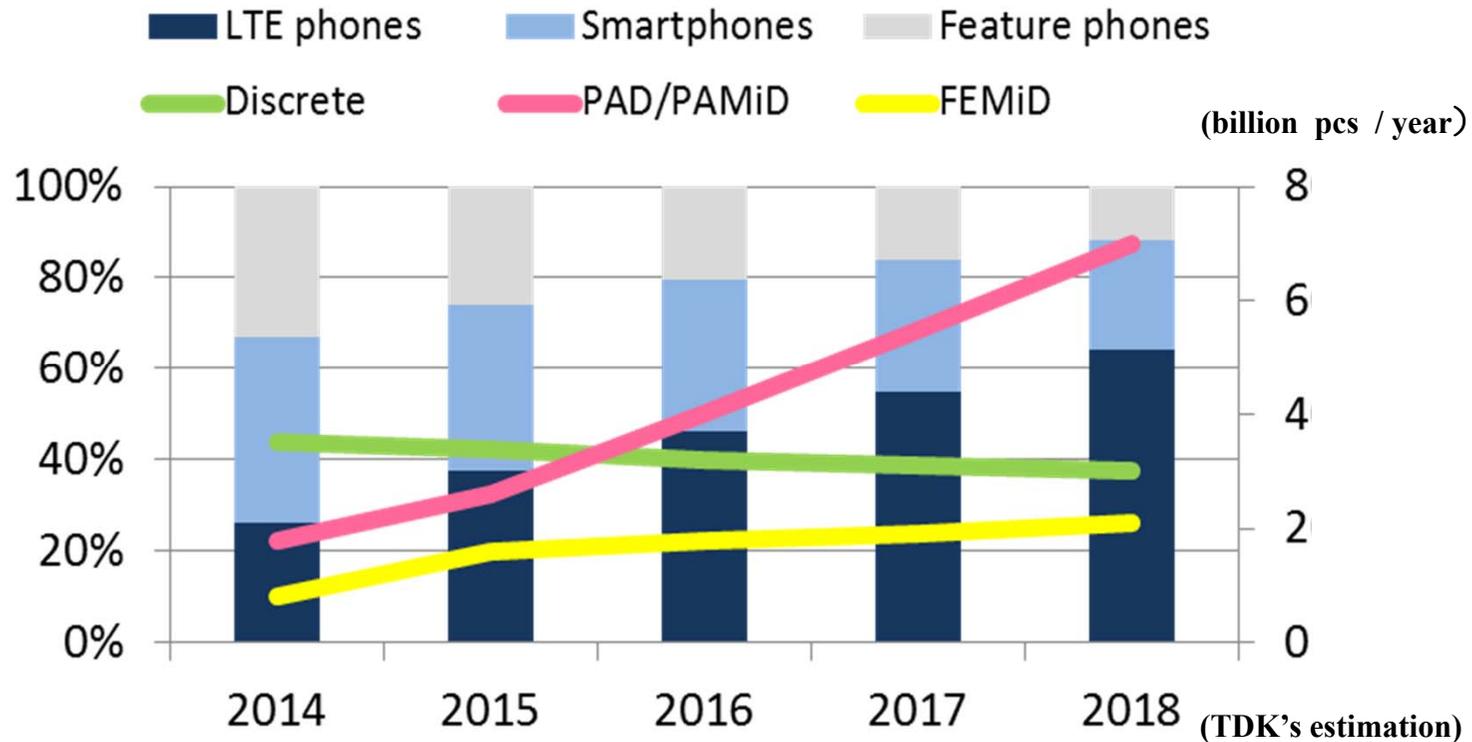
◆Convivial party (11:35 - 12:30)

Priority Markets and Strategic Products

**Senior Vice President
(General Manager of Electronic Components
Sales & Marketing Group)**

Noboru Saito

Progression of mobile phone production and RF components



The increasing amount of information transmitted via mobile communications necessitates the use of faster communication networks and accelerates the spread of LTE user equipment.

Increasingly complex circuits used in LTE user equipment require components with reduced footprints, which is fuelling a growing demand for components for PAD, PAMiD and FEMiD modules.

Medium-term strategies targeting the ICT market

Market drivers are

LTE-4G • 5G

Change points:

Additional increase in number of bands

Efficient power management

Technology

Strategic products

Thin-film technology

Packaging technology

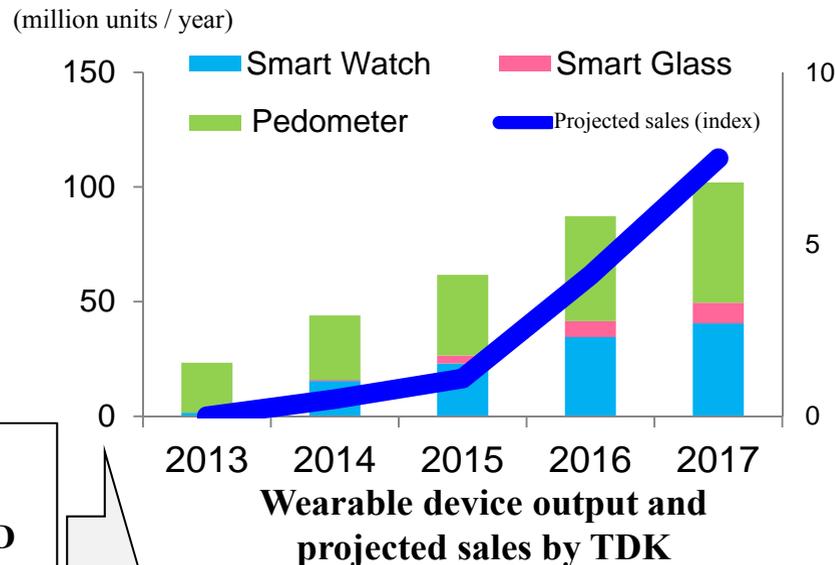
SESUB

- ◆ **Narrow pass band filters**
BAW / SAW
- ◆ **Components for PAMiD, FEMiD**
BAW / SAW /
Thin-film products
- ◆ **Power management components**
Power inductors /
Power management modules

IC collaboration

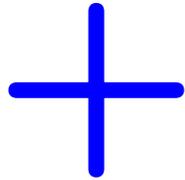
Spread of wearable devices

*Based on estimates by TDK



Deployment of strategic products involves providing components that meet the requirements for wearable devices

**IC
collaboration**

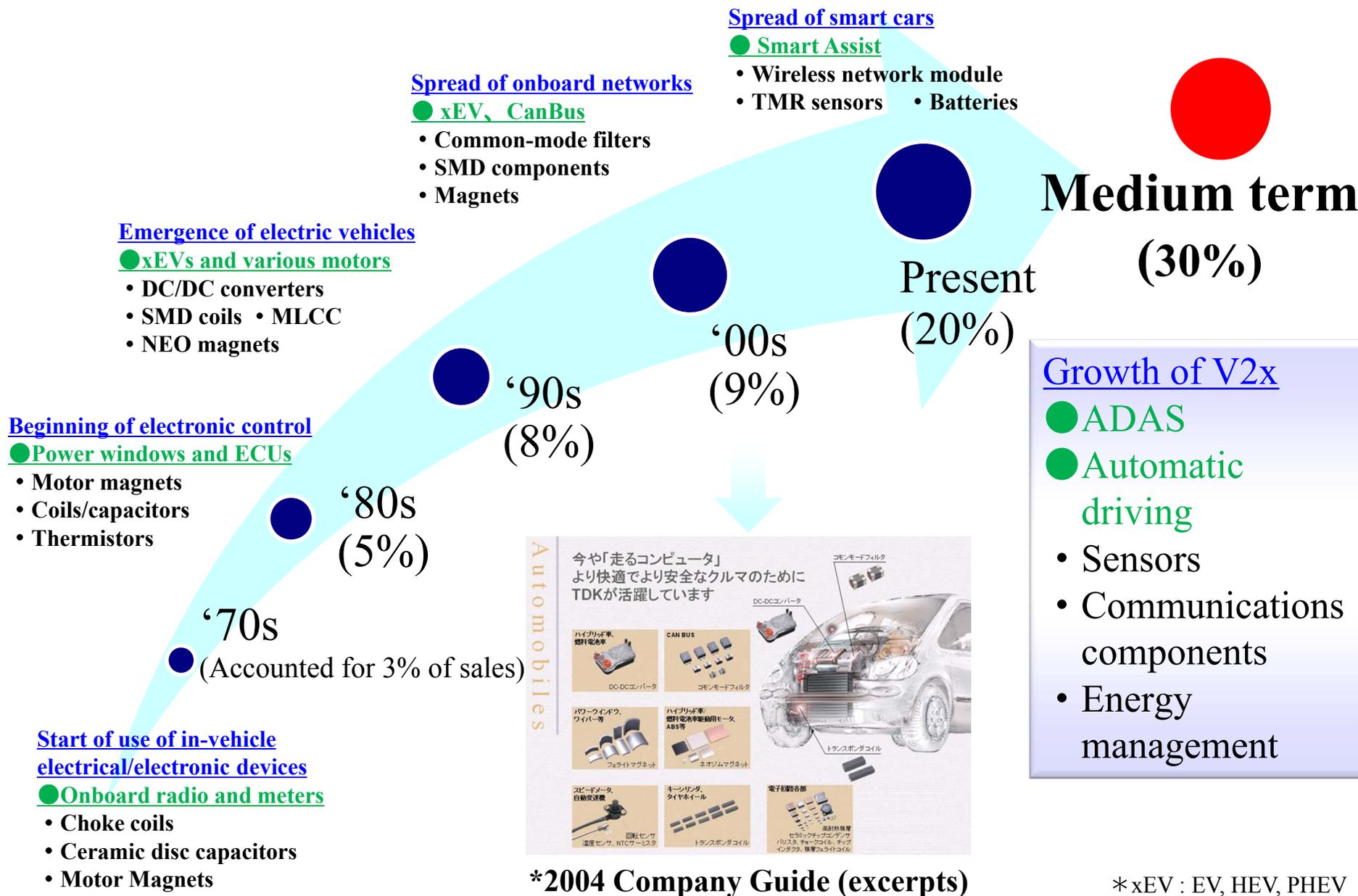


Function	IC makers (including PA)	Strategic products (example)
RF use and Power line use	Company C Company T Company N Company P Company K Company V Company L Company X	■ Thin film products Power inductors, Filters etc.
		■ BAW / SAW / Discrete
		■ PAD / PAMiD / FEMiD
		■ SESUB Module (RF, Power management)

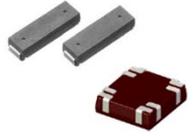
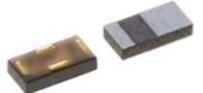
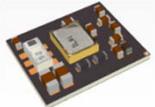
**Sales
promotion for
existing
products**

Products with notable features
Lithium polymer battery
Wireless charging unit (WLC)
Low-consumption Bluetooth® module (BLE)
Film photovoltaics
Various sensors

TDK sales over time in the automobile market



Deployment of existing products

Existing products	Newly developed products
Common Mode Filters 	<ul style="list-style-type: none"> • Ethernet common-mode filters • Suitable for location-free production 
Capacitors 	<ul style="list-style-type: none"> • Guaranteed operation at high temp. (200°C) • Capacitor with resin electrodes 
Inductive Devices (Ferrite type, Metal type)	Power Inductors <ul style="list-style-type: none"> • Guaranteed operation at high temp. (150°C) 
	<ul style="list-style-type: none"> • Smart keys • Transponder inductors for TPMS 
Deployment of communications components for automobile applications	<ul style="list-style-type: none"> • SAW Devices 
	<ul style="list-style-type: none"> • Thin-film high frequency filters 
	<ul style="list-style-type: none"> • Bluetooth® Modules 

Custom-designed products



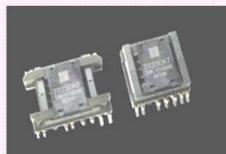
Power Supply Units



DC-DC Converter



Battery Charger



IGBT Transformer

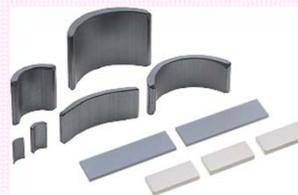


Wireless Charging Devices for Vehicles



Lithium-Ion Battery

Various Motors



Magnets

- Dysprosium (Dy)-free neodymium magnets
- Lanthanum (La)-free and cobalt (Co)-free ferrite magnets

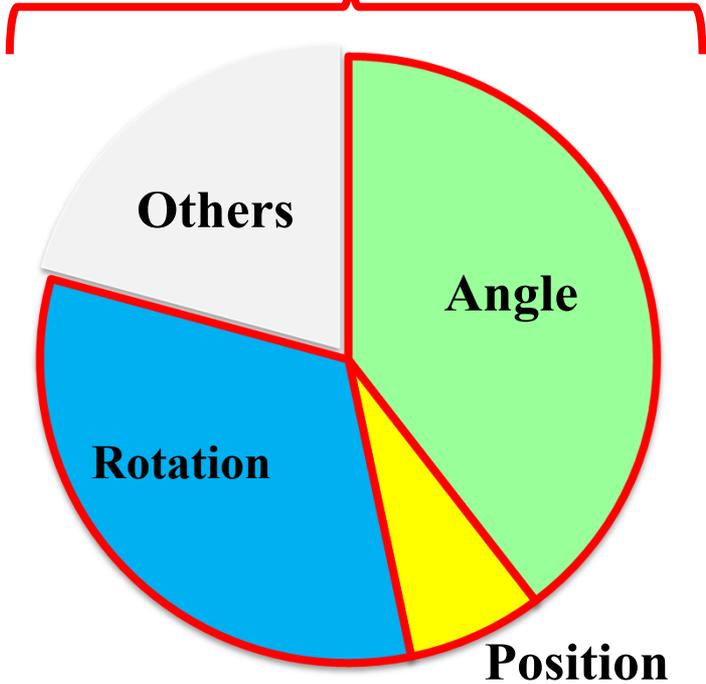
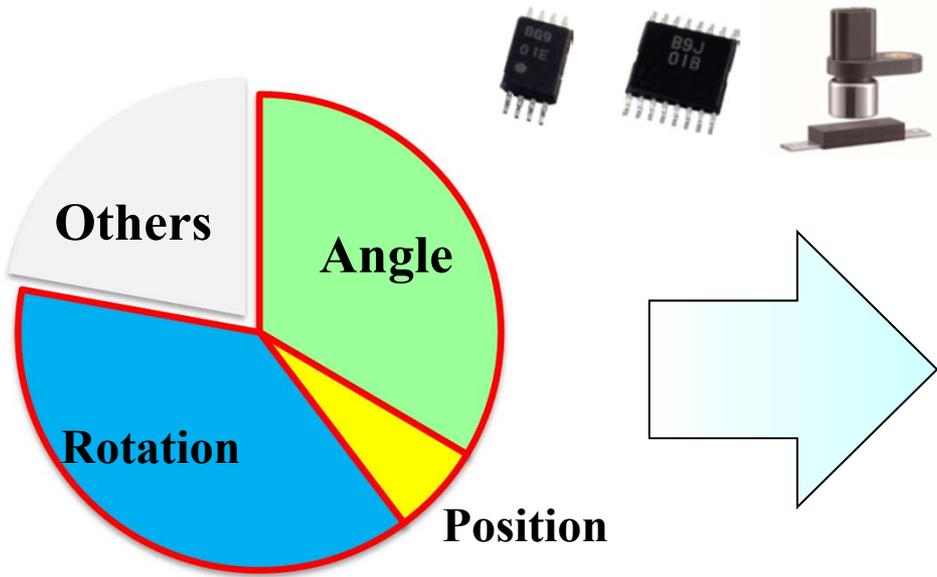
Sensors



Gear Tooth/ Pressure / Current / Temperature

New products
Magnetic Sensors
(TMR/GMR)

High-accuracy sensing
 by TMR/GMR sensors



CY2014 90 billion yen

CY2018 120 billion yen

Demand breakdown for onboard magnetic sensors, by use (billion Yen /Year)

Source: IHS's materials

Wireless-charging and TMR/GMR sensors for industrial equipment



Target equipment (example)

Hybrid buses

Catenary-free streetcars

Cable-less elevators

Target equipment (example)

Linear motor encoders

Industrial robots



Electronic components for renewable energy applications

CeraLink



Film capacitors
Aluminum capacitors



Magnets for wind
power generator



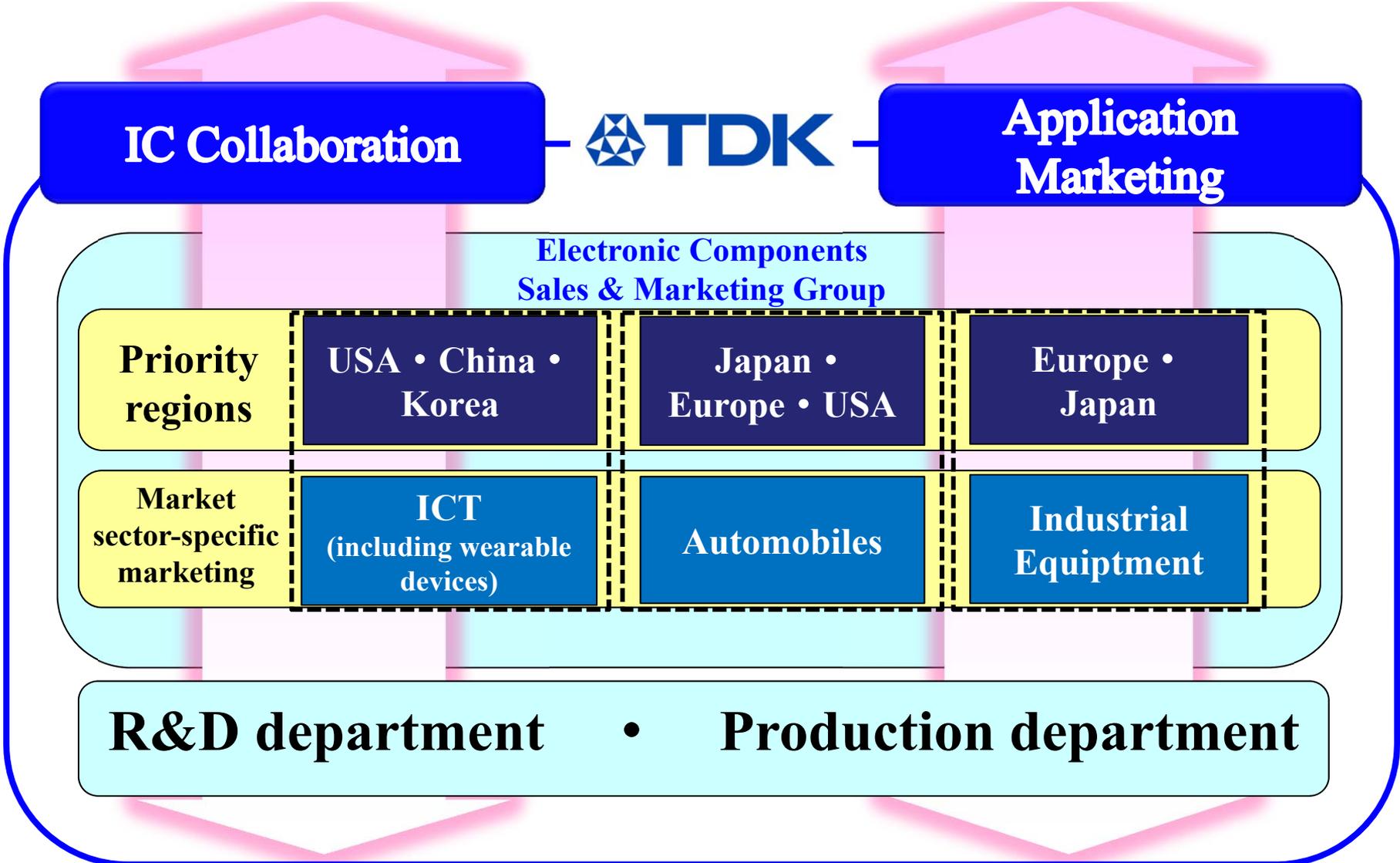
High performance ferrite cores



Filters • Varistors • Arresters

Sensors

Building Customer Value



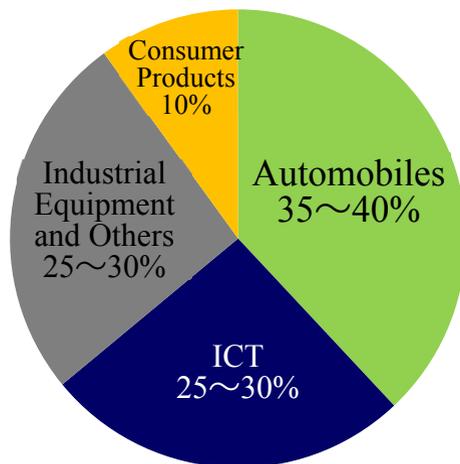
Strategy of Priority Five Businesses

Inductive Devices
High Frequency Components
Piezoelectric Material Products
Rechargeable Batteries
HDD Heads

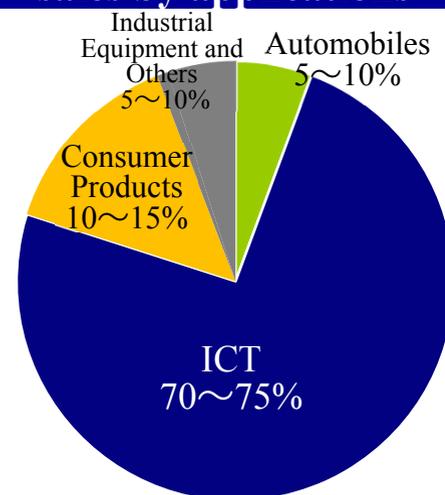
Executive Vice President
Hiroyuki Uemura

Inductive Devices

Inductive device sales by applications



Metal power inductor sales by applications



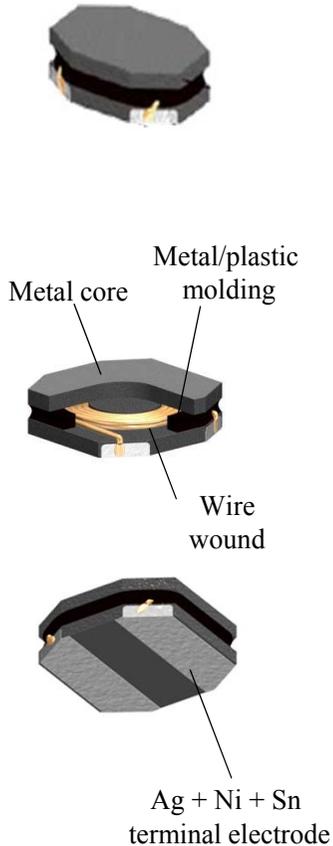
【 Metal inductor production engineering 】

Engineering	Feature	Characteristic		Major product	Competitor
Wire wound	Large current High reliability	Size	2016~1717	VLS CLF SPM	Company C Company S Company T Company V
		Frequency	~10MHz		
		Current	3~10A		
Thin film (plating)	Large current Small/Low profile	Size	1608 height 0.5mm	TFM	Company S
		Frequency	~10MHz		
		Current	2~6A		
Multilayer	Small Low profile Suitable for high-frequency applications	Size	1005~2016	MLS MLP	Company T
		Frequency	~200MHz		
		Current	~2A		

Features of metal power inductors

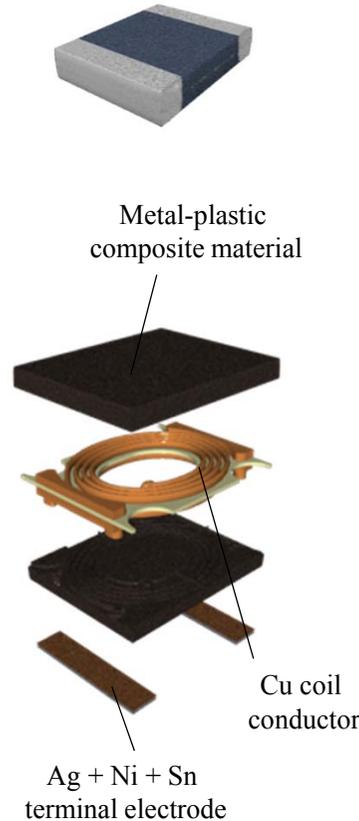
Metal Wire Wound
VLS-HB Series

Large current
Broad inductance range



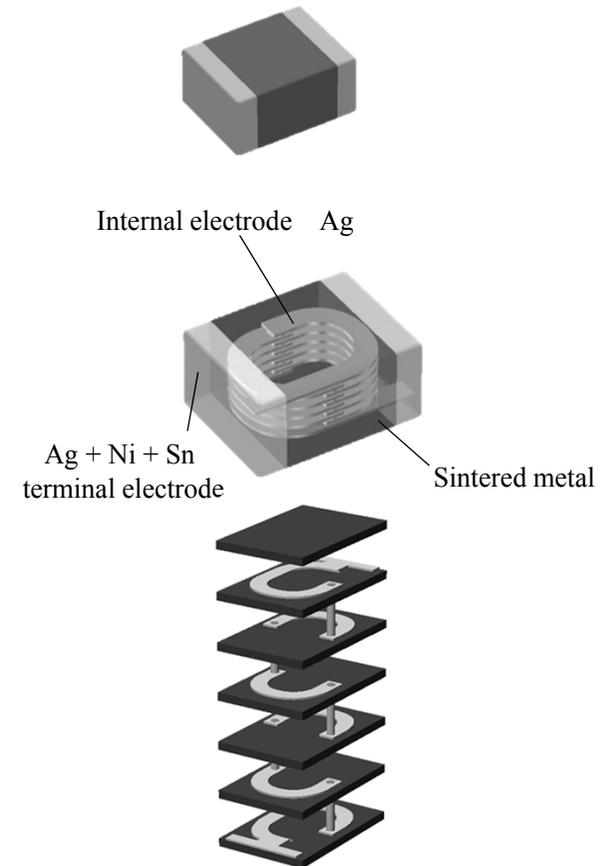
Metal Thin Film (plating)
TFM Series

Small/Low profile
Large current



Metal Multilayer
MLS Series

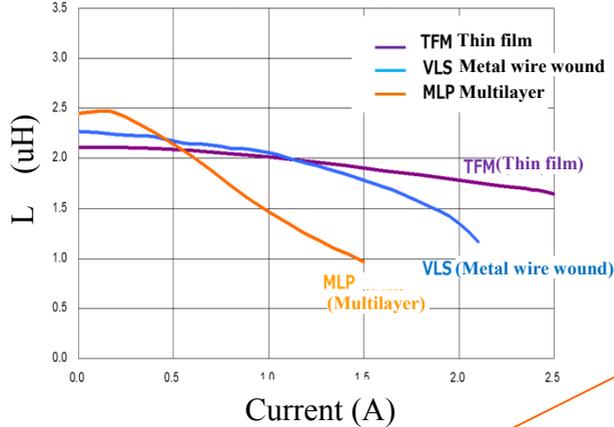
Small/Low profile
Low loss



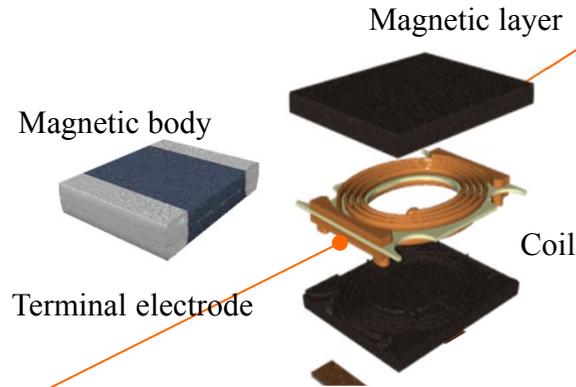
Structure and features of thin-film metal inductor/TFM

Structure

Reduced current-dependent characteristic variation
→ Suitable for large-current applications

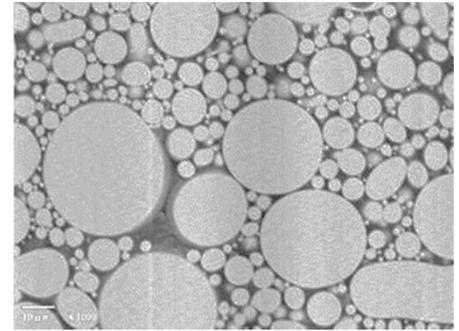


Structure

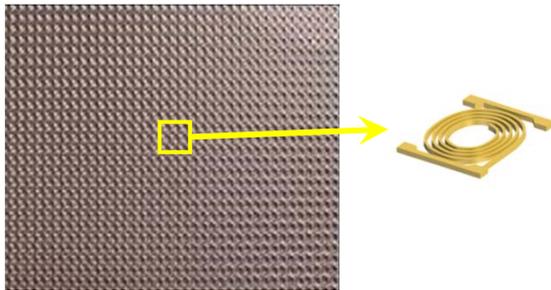


Magnetic metal material

High-dispersion and high-filling technique used to achieve high μ

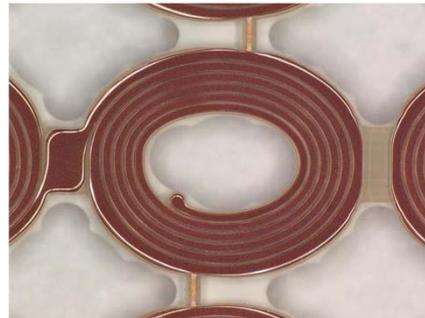


Coil substrate



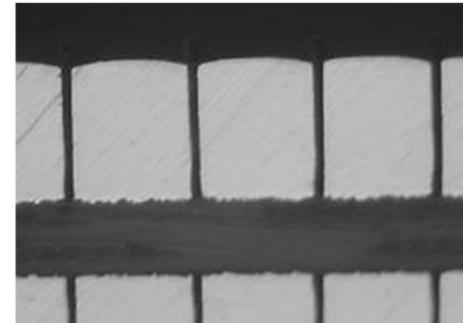
Substrate process to improve production efficiency

Coil conductor

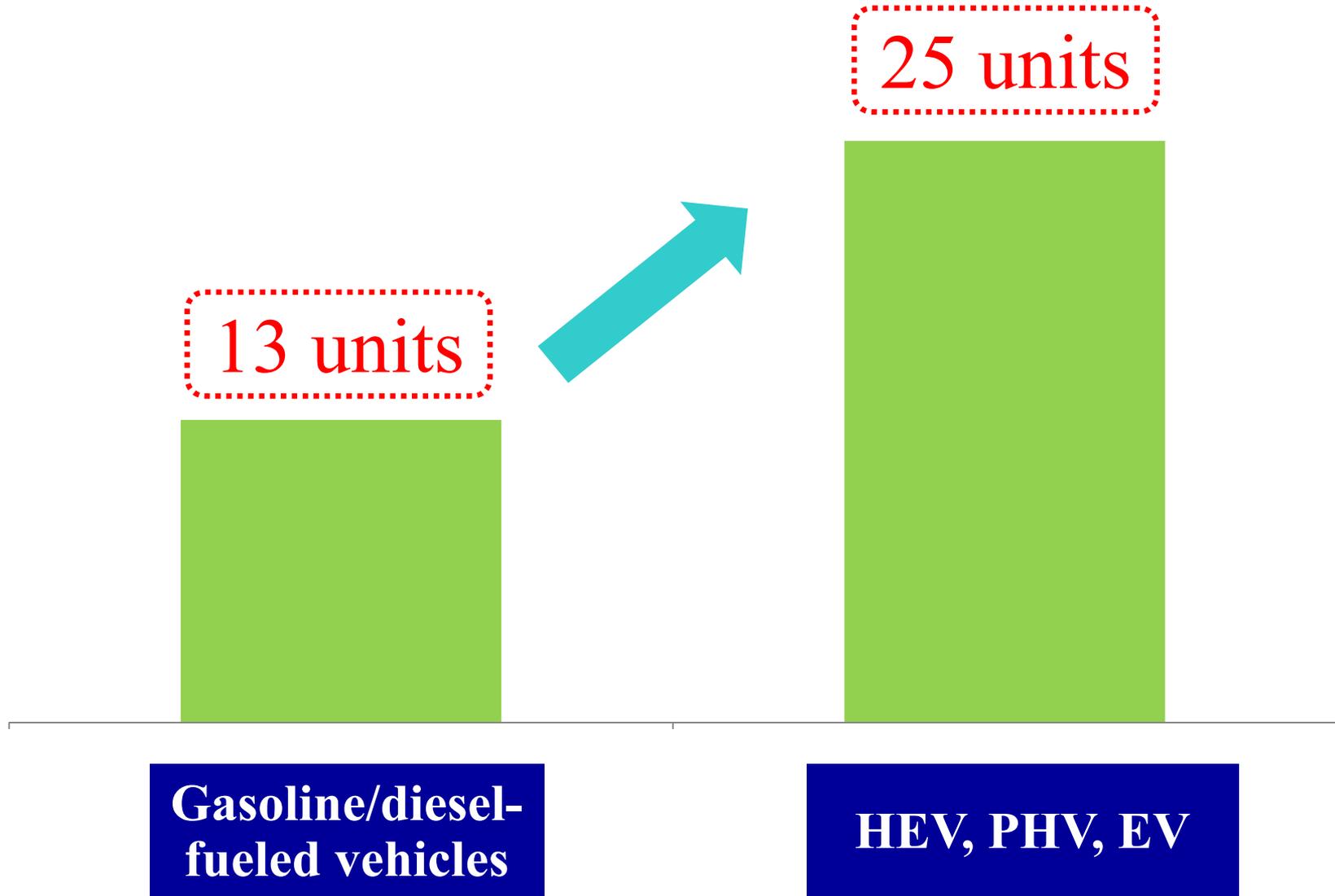


High-density coil conductor formed by micro-patterning

Coil conductor cross section



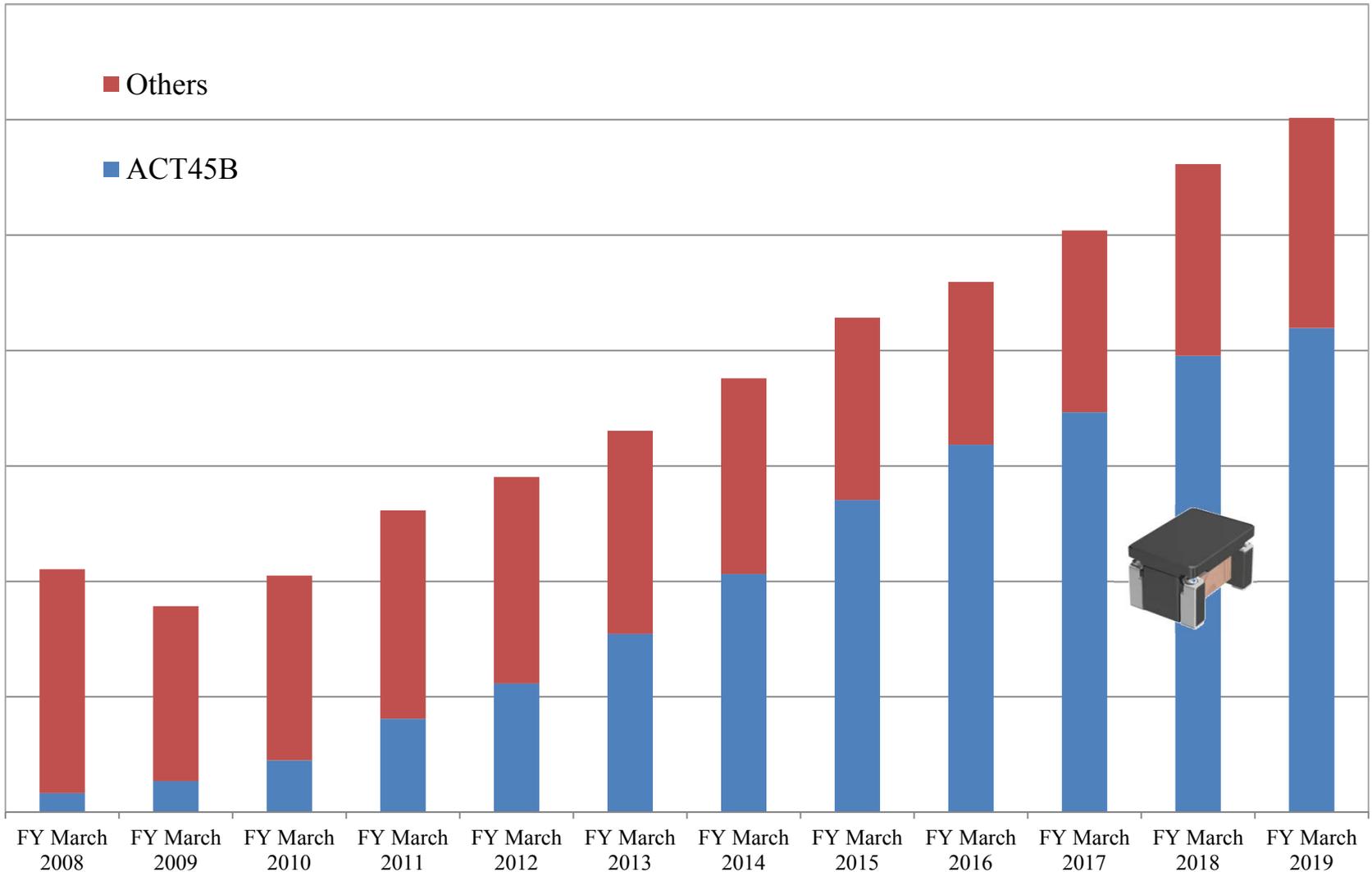
High-density winding and low-resistance coil enabled by newly developed high-aspect and high-precision plating technique



※TDK's estimation

CAN filter sales trends

Quantity



① Enhancing metal inductors

Lineup comprising a full range of thin-film, multilayer and wire wound inductors, notably with an increased line of TDK's flagship thin-film inductors

② Comprehensive application of integrated location-free production lines

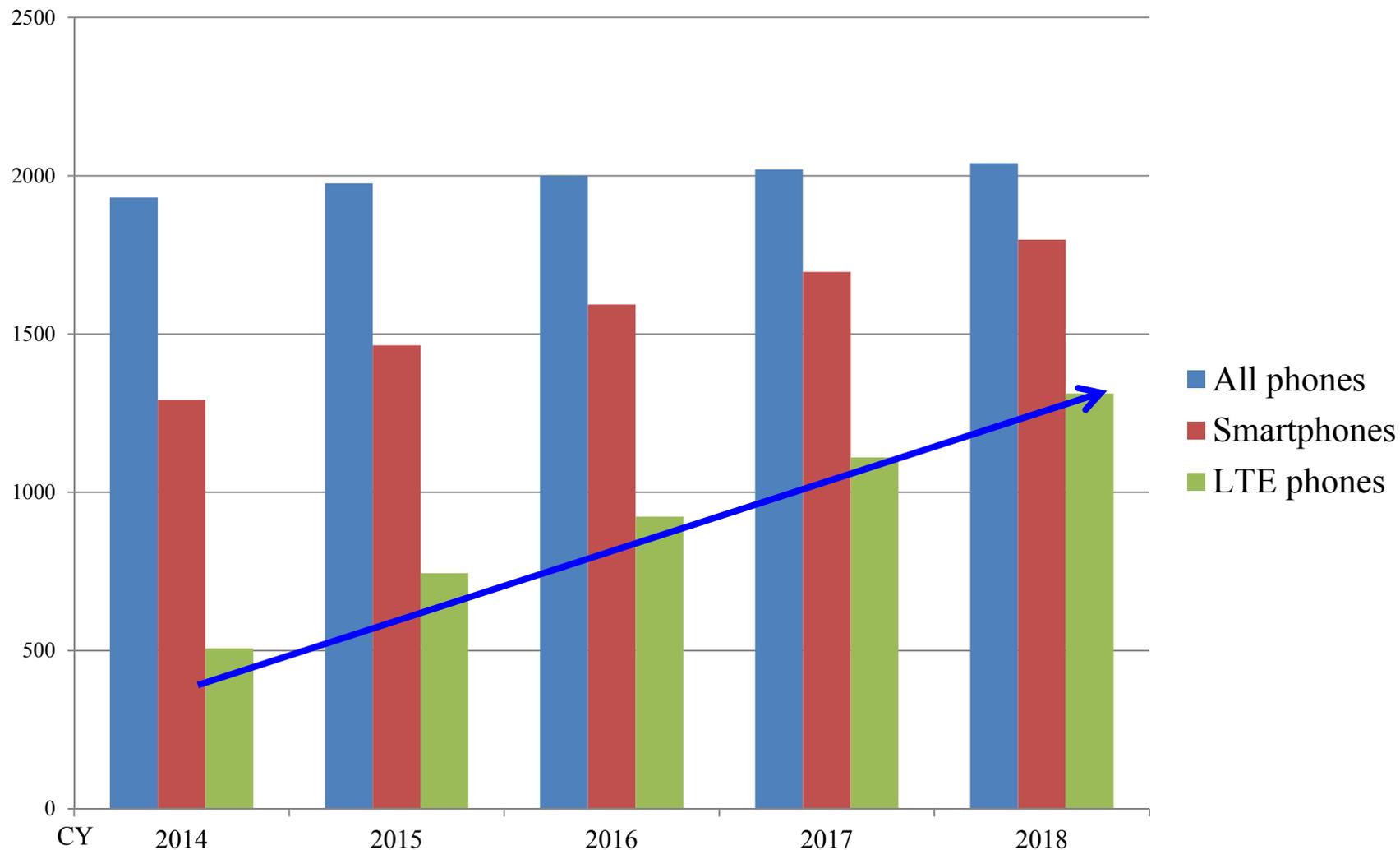
Relocating part of manufacturing sites from China to Japan to be considered according to foreign exchange movements

③ Strengthening collaborations with IC manufacturers

High Frequency Components

Mobile phone market overview

Phones 【M pcs】

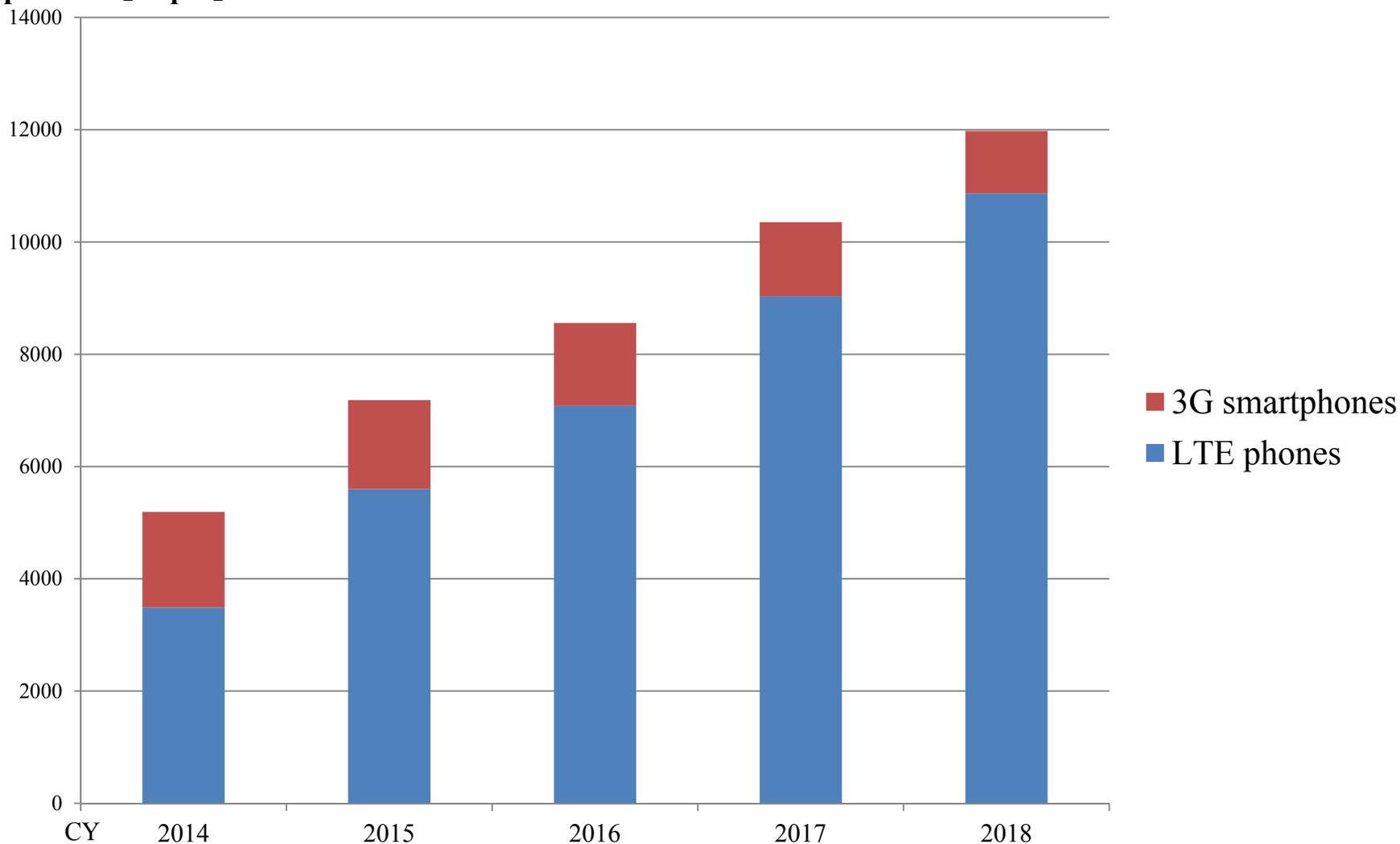


※TDK's estimation

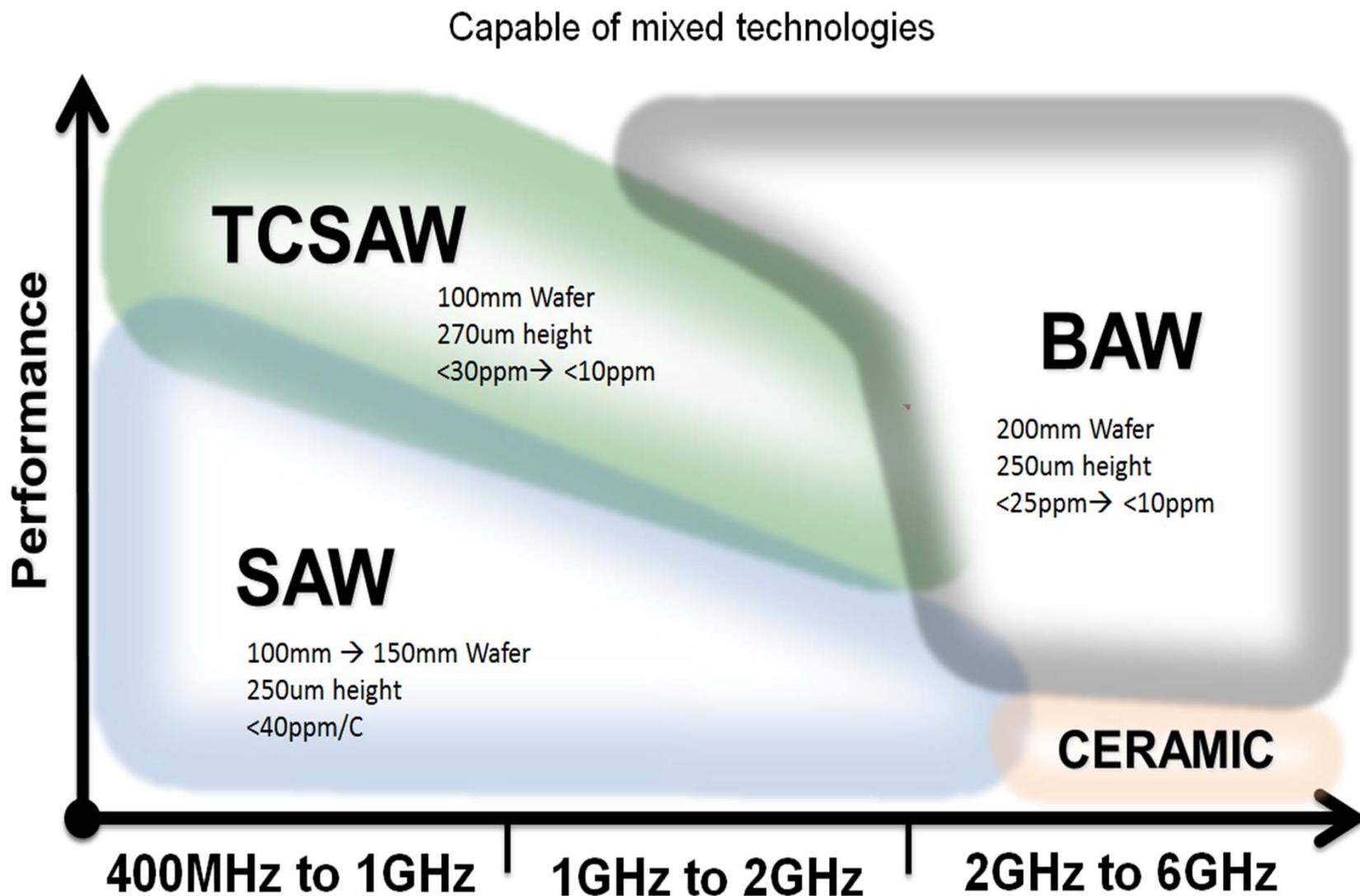
Duplexer market expansion by the use of LTE



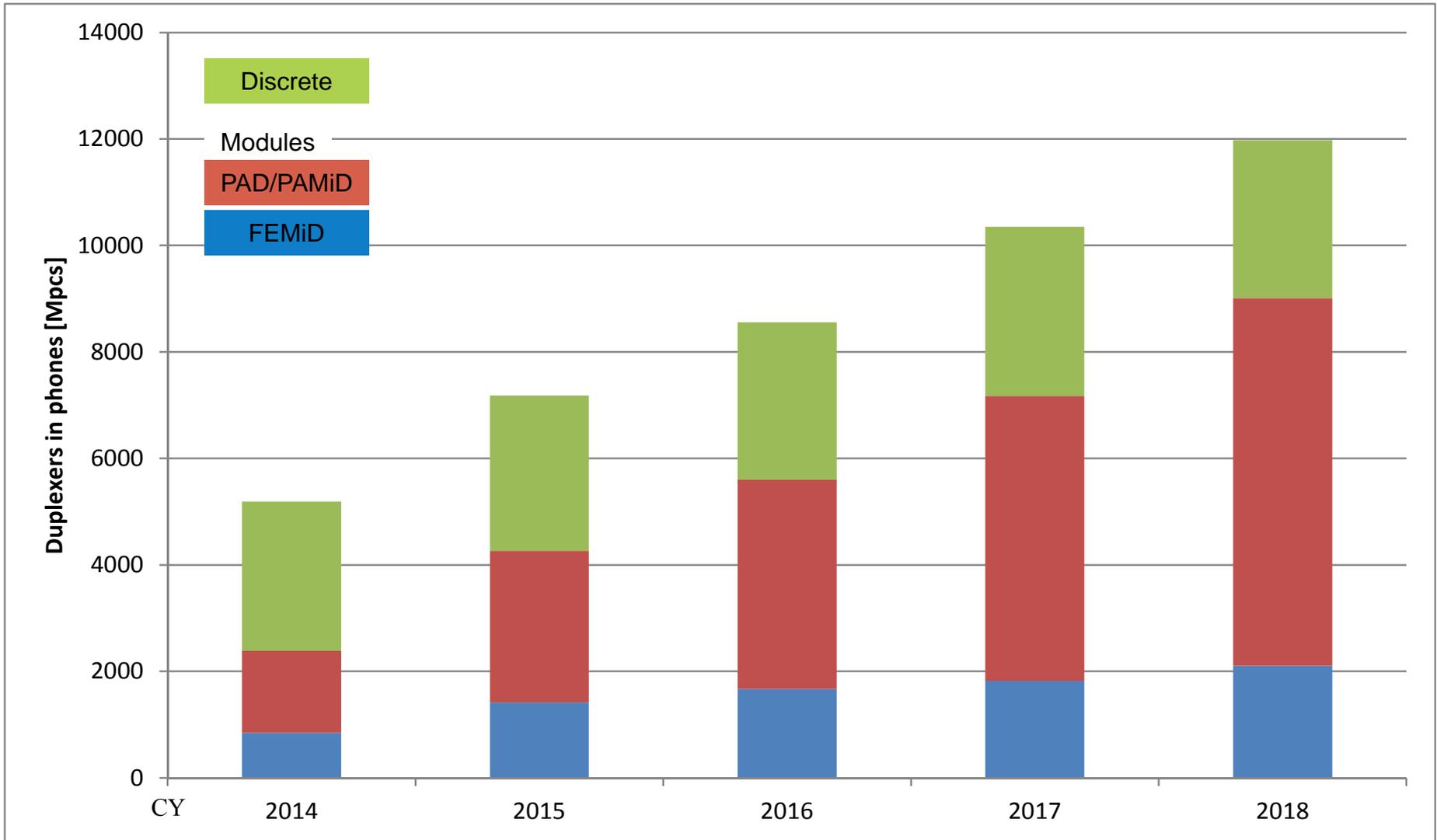
Duplexers 【M pcs】



※TDK's estimation



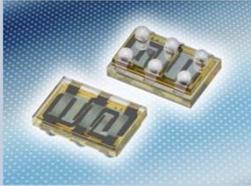
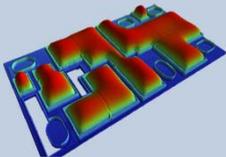
Discrete components versus modules in duplexer market



※TDK's estimation

TDK's advanced packaging technologies



Packaging Technology	Feature	Use	Height
CSSP 	General-purpose package for discrete components (in volume production)	Mobile phones Telematics	0.6 mm
DSSP 	Small package for SAW (in volume production)	Modules for mobile phones	0.4 mm
TFAP 	Next-generation wafer-level package for SAW and BAW (in preparation for volume production)	Modules for next-generation mobile phones	0.25 mm

① Making filters higher value-added and suitable for modules

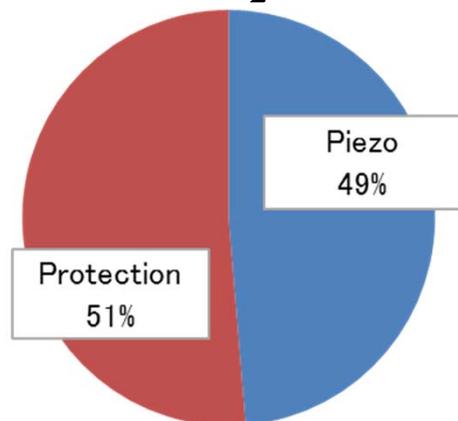
- SAW, TCSAW and BAW filters to cover the entire range
- New packages for shifting toward smaller size and lower profile and for simplifying the subsequent process

② Strengthen relationships with IC manufacturers

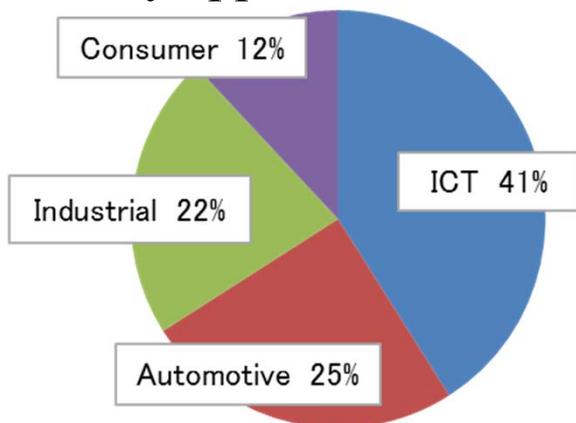
- Providing solutions drawing on reference design-in
- Collaboration with PA manufacturers to meet PAD/PAMiD market needs

Piezoelectric Material Products

【Sales breakdown】



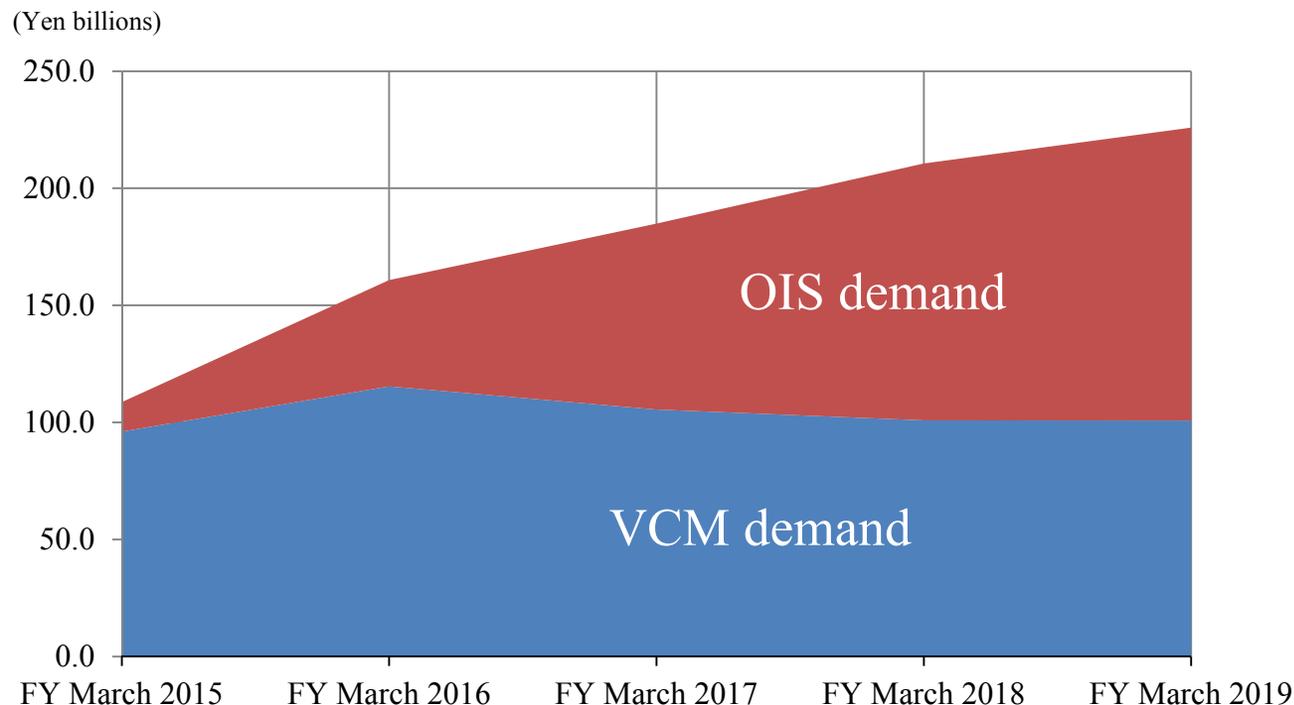
【Sales by applications】



Application	Main Products
ICT	Camera module actuators Surge arresters Chip components (varistors and NTCs)
Automobiles	Piezo injectors Chip components (varistors and NTCs) PTC
Industrial Equipment and Others	Disc varistors PTC Chip components (varistors and NTCs)
Consumer Products	Piezo actuators PTC Disc varistors

- Growth in ICT market principally with camera module actuators
- Ceramic protection components cover all areas of application

Demand for Camera Module Actuators



※TDK's estimation

Demand for high-performance OIS camera module actuators is expected to grow from now on. TDK's OIS sales will be expanded to achieve overall business growth.

- ① **Growth of OIS camera module actuator products**
- ② **Promoting development of Ceralink for the automotive industry**
- ③ **TDK has the largest share of the market for ceramic protection components (arresters, varistors, PTCs and chip components) and earns profits stably from this market**

Strategy of Priority Five Businesses

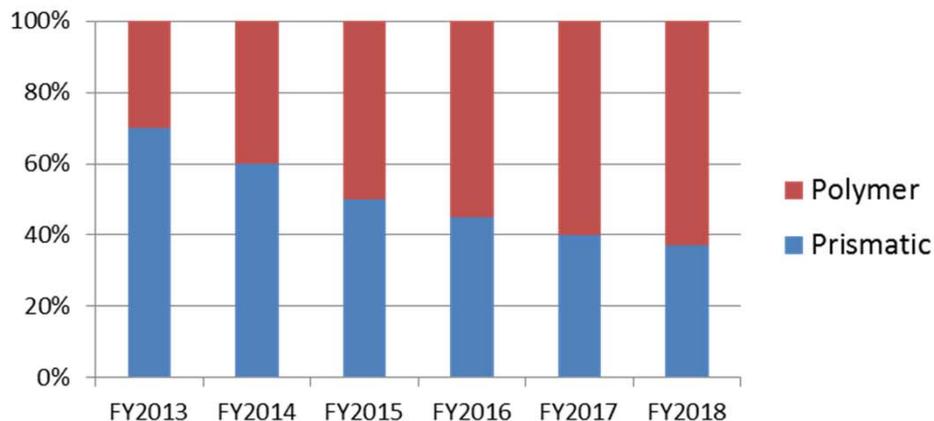
Inductive Devices
High Frequency Components
Piezoelectric Material Products
Rechargeable Batteries
HDD Heads

Senior Vice President
Robin Zeng

We expect higher growth of Polymer Battery demand in next mid-term

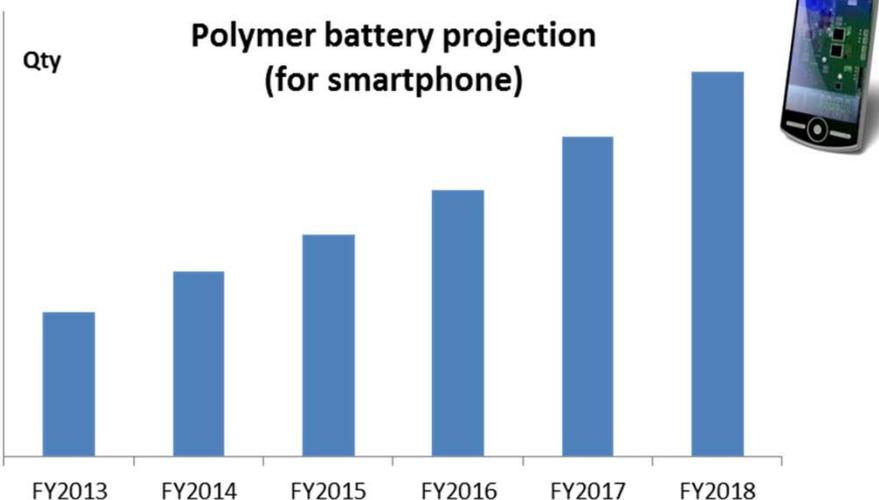
LIB cells demand (for Cellular phones)

Polymer penetration : 30% > over 60%



※TDK's estimation

Polymer battery projection (for smartphone)



※TDK's estimation

- ◆ Smart Phone market growth rate up to 20% per annual
- ◆ Tablet & Notebook PC growth up to 10% per annual
- ◆ Slim type notebook PC will cause more demand of polymer battery transfer from cylindrical battery

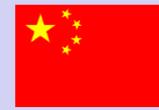


FY2013 : FY March 2014

Plan to increase market share by expanding customer base to adapt the change of market and business environment



USA



China



Korea



Japan

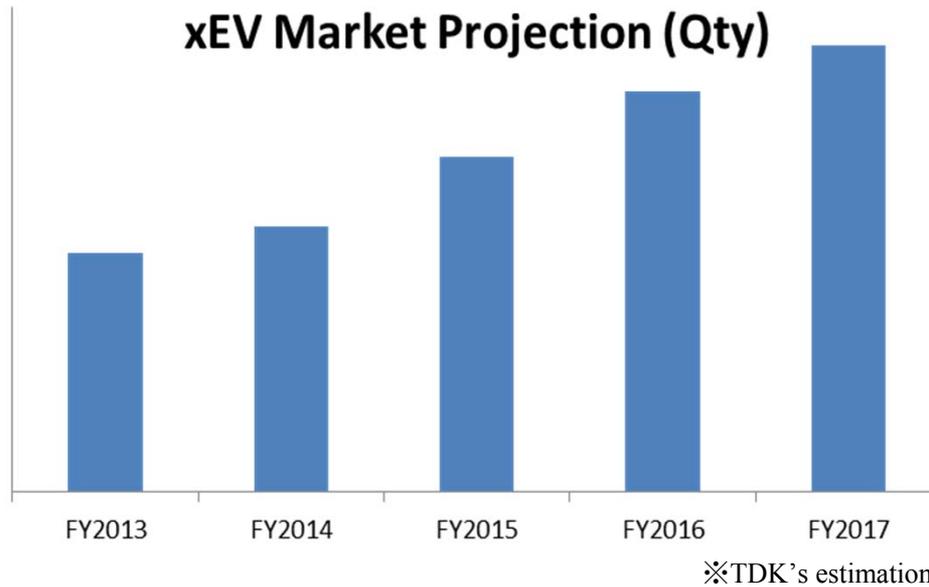
- ◆ Provide solution to customers from battery cell to pack design



- ◆ Strengthen R&D activities in new material development, manufacturing technology, design development

- ◆ Cost competitiveness

- Continue to improve manufacturing efficiency to enhance our competitive advantage
- Utilize in-house developed equipment for low cost and process enhancement



- ◆ Huge potential of market growth in EV/ESS
- ◆ EV : 48V, PHEV, EREV, BEV initial introduction
- ◆ ESS : Smart grid, home storage, large scale ESS for frequency regular and China special solar plant/wind farm are on early introduction stage



Aim to become a technology solution provider of Battery Energy Storage System (BESS), provide the best cost to performance service for customers

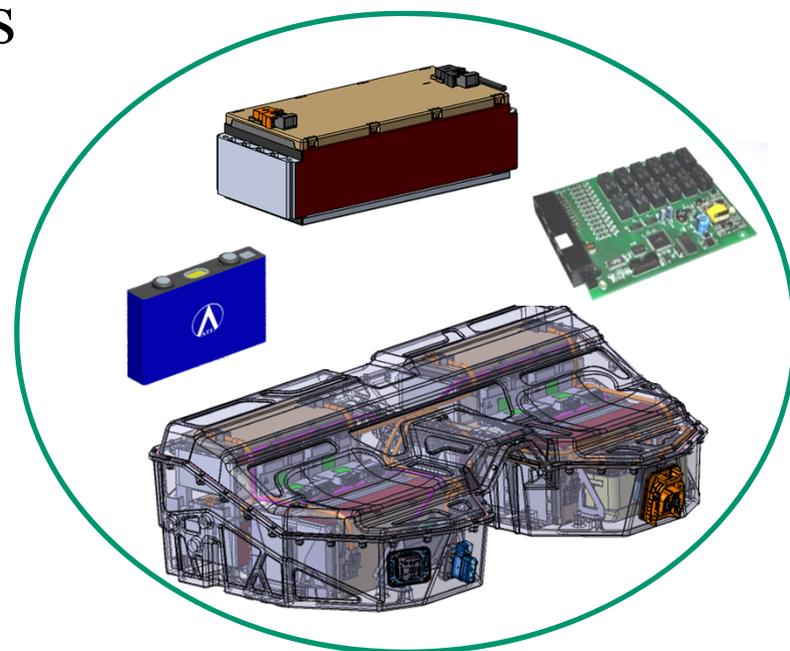
◆ Material Research

◆ Development and manufacturing of

- Battery cells
- Battery Module
- Battery Management System
- Battery Pack

◆ Reuse & Recycle (value chain)

- Invest one Chinese recycle company for customer service



Three factors to enhance competitive advantage

**Superior
Customer Service**

**Technology
Advancement**

**Operation
Excellence**

Differentiation in products,
process, and equipment

Flexibility, Efficiency, and
Quality control

- ◆ Battery is active safety device with the combination of technology of chemistry, material, electronics, mechanical and thermal management etc. It may cause safety event in the field and the larger battery has higher risk.

Our Quality Policy to overcome the risk

> Start from material intrinsic safety to design battery to manufacturing with quality system build in. Especially on FMEA* system applying to design and process

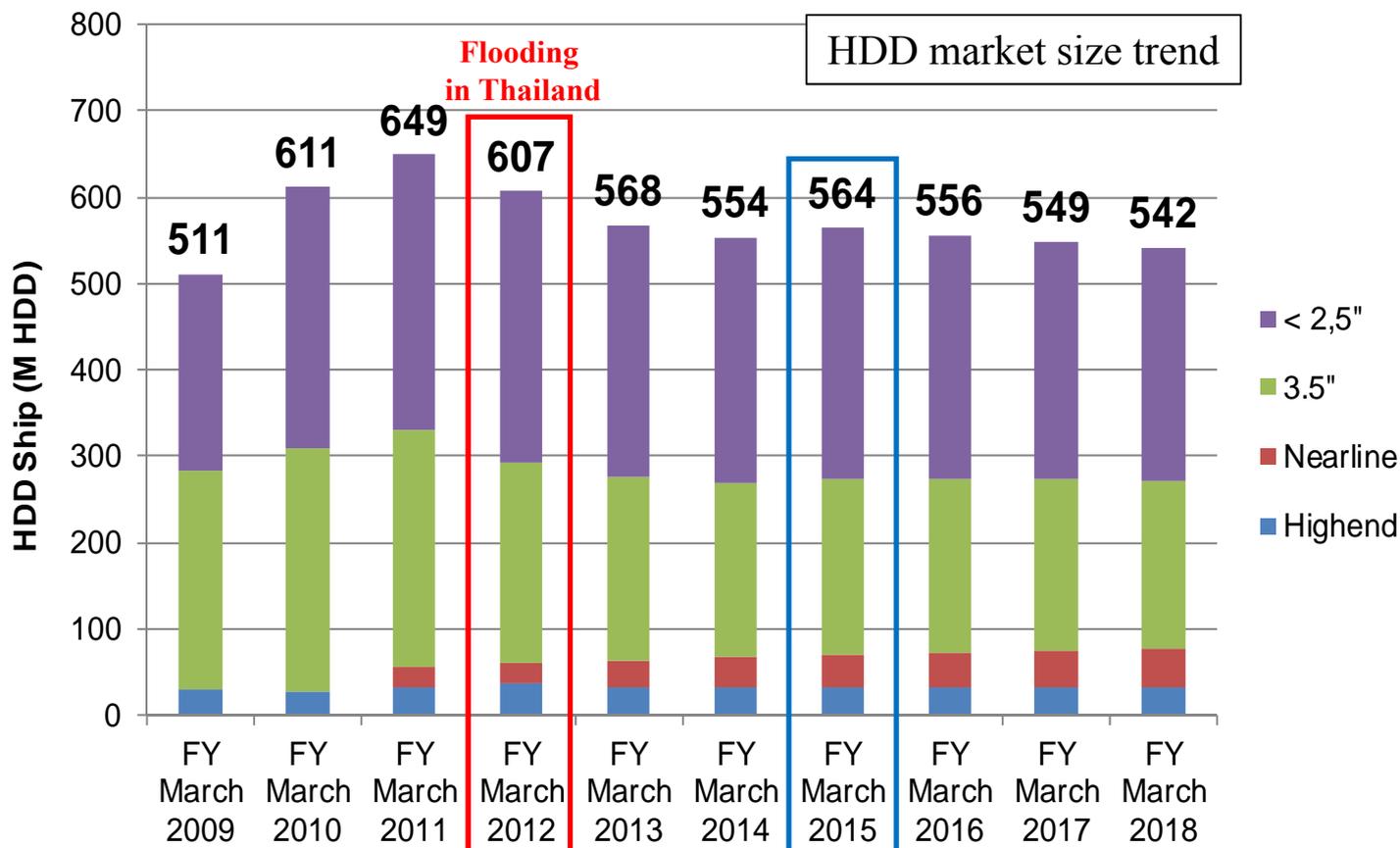
*FMEA : Failure Mode and Effect Analysis

Strategy of Priority Five Businesses

Inductive Devices
High Frequency Components
Piezoelectric Material Products
Rechargeable Batteries
HDD Heads

**Corporate Officer
Shigenao Ishiguro**

< About the HDD market size and changes >



←→ **Growth in parallel with PC**
←→ **Transition period**
←→ **Tapping the high-capacity storage market**

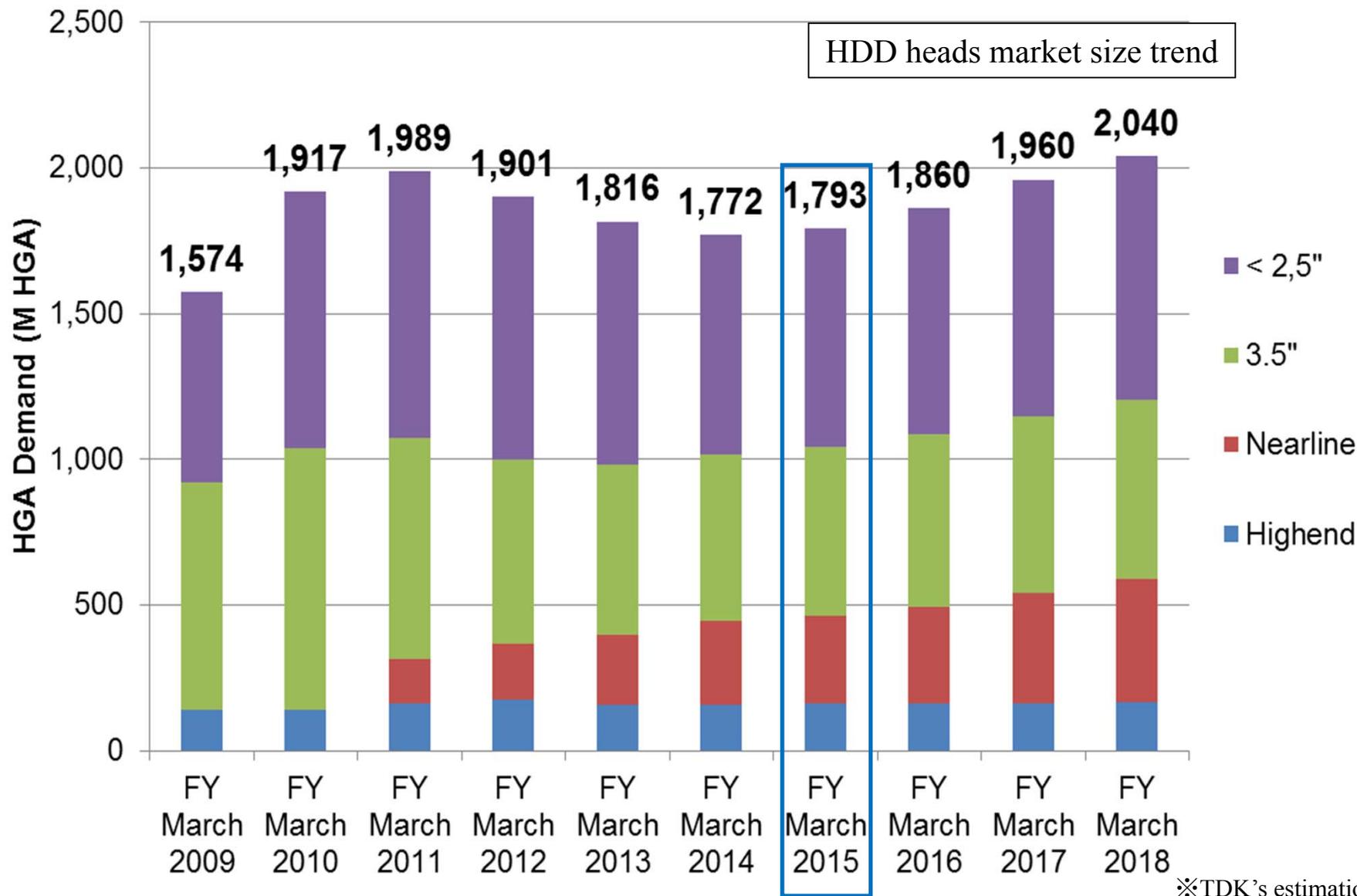
※TDK's estimation

- ❑ **HDD market shifting from mobility to capacity**
- ❑ **High-capacity HDDs to sustain the era of big data**

<Key Success Factors>

- 1) Continued development of new head products for multi-disk HDD**
- 2) Accelerated development of assisted recording (with TAMR being most promising) and establishment of the TAMR business**

About the HDD heads market



※TDK's estimation

- ① **–2014: Starting up high-capacity storage business**
- ② **–2017: Introduce SMR*1 and DSA*2 technologies for new multi-disk HDD**
- ③ **2017–: Target set at 50% share of TAMR head market**

*1: Shingle MR

*2: Dual Stage Actuator

Enhancing Financial Strength

**Corporate Officer
Takakazu Momozuka**

- ① **Improve profitability by expanding priority businesses**

- ② **Improve efficiency in general and administrative expenses and R&D expenses**

- ③ **Financial strategy**

Improve profitability by expanding priority businesses



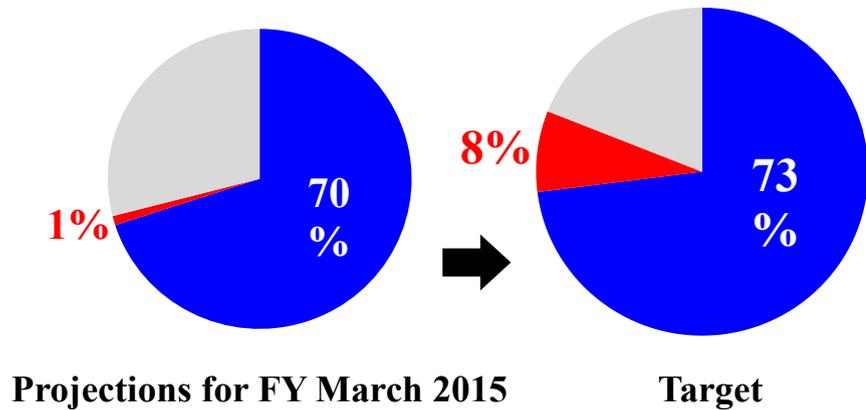
Priority businesses

■ Priority Five Businesses

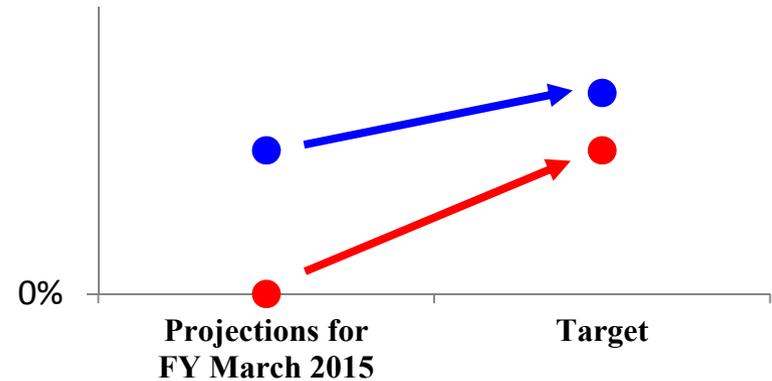
■ New Businesses

■ Others

Business size expansion (sales breakdown)



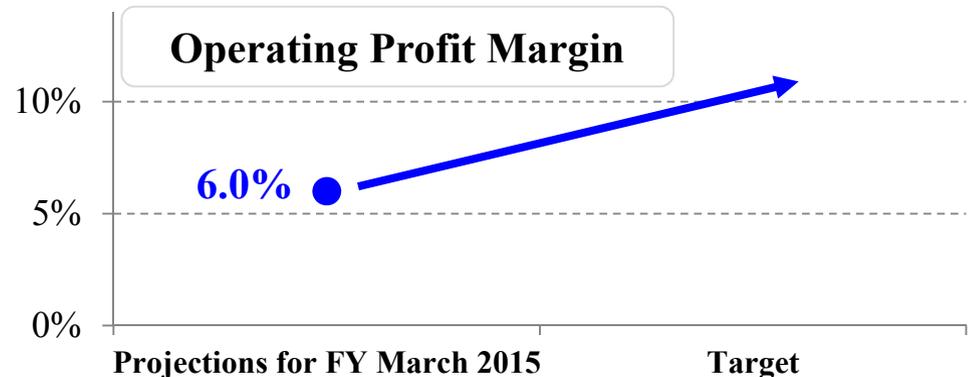
Improved profitability (operating profit margin)



Company-wide

	Projections for FY March 2015	Target
OP margin	6.0%	Over 10%

Operating Profit Margin



Projections for FY March 2015	Sales percentage
SGA expenses (excluding R&D expenses)	12.5%
R&D expenses	6.5%
SGA expenses Total	19.0%

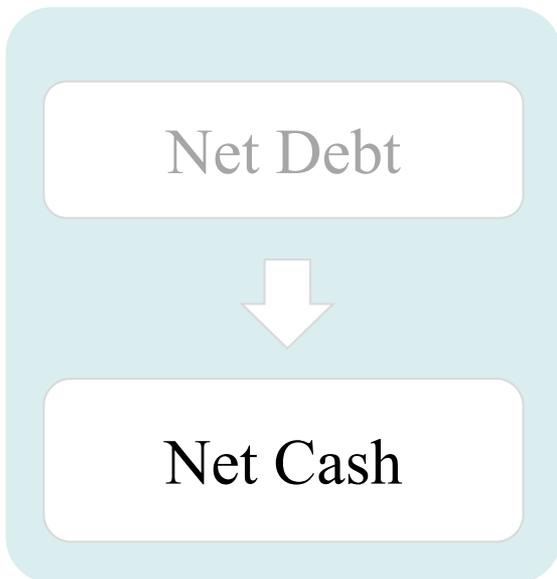


Measures

- ✓ **Promote reforms for Head Office functions**
 - Speedy business operations enabled by delegation.
 - Efficiency improvements by consolidating service divisions
- ✓ **Review the R&D system at Head Office**
 - Shifting toward a global R&D system
 - Enhancing business strength by making development efforts within local divisions
 - Medium- to long-term development themes promoted by Head office



Improve profitability by reducing the percentage of general management expenses and improving development efficiency



Return to shareholders

Growth investment

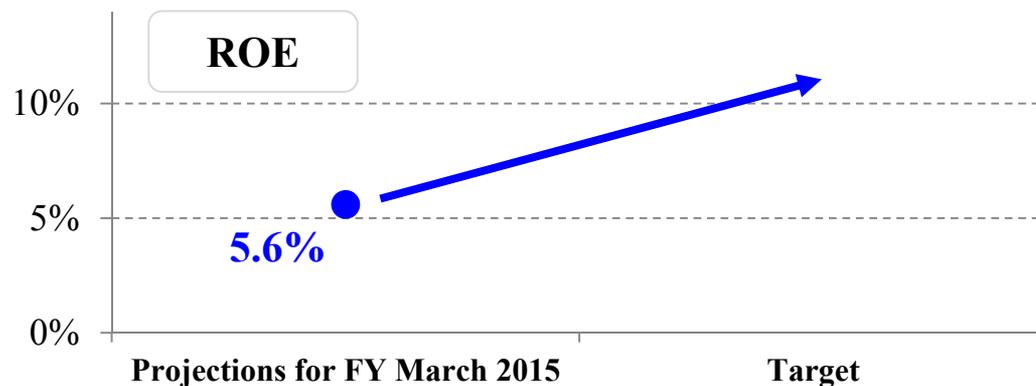
Dividend policy

Strive to achieve stable dividend increases through growth in the earnings per share figure

Invest funds into the development of new products and new businesses

Consider the acquisition of own share, in addition to dividends, as an option to provide returns to stockholders

	Projections for FY March 2015	Target
ROE	5.6%	Over 10%



New Development Areas/ Summary

**President and CEO
Takehiro Kamigama**

- Development functions of Head Office in Japan focus principally on material development and other medium- to long-term themes
- Overseas group companies strengthen their development functions beginning with research projects

China (Shanghai)

- EMC support
- Proposing optimal components

Japan

- Development of new materials
- Development of innovative engineering methods
- Development of new products

Europe (Munich)

R&D on products and technologies for automobiles

China (Xiamen)

Material (product) development meeting the needs of local customers

San Jose

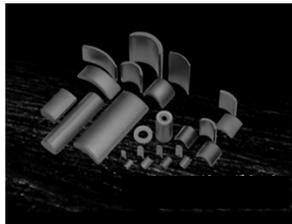
USA (San Jose)

R&D on products and technologies meeting the needs of the ICT market

- Strengthen power unit components for next-generation vehicles(BEV/HEV/PHV/FCV)
- Promote the sales of power-related components drawing on magnetic technology, which is TDK's core competence

Automotive field 1 to 2 years

3 to 5 years



Ferrite magnets



HEV motor-generators



High-performance neodymium magnets

Rare-earth-free/strongest magnetic materials for drive motors

Lead-free piezoelectric materials (thin-film, bulk)

Secondary batteries for xEVs (high-safety technology)

Dy-free magnets with Nd reduced by half for drive motors

Lead-free piezoelectric material (Ceralink)

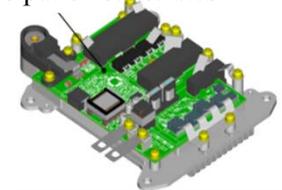
High-efficiency small DC-DC converters & chargers

Secondary batteries for xEVs (lithium ion)

Wireless charging systems for xEVs

● Performance improvements by grain-boundary composition control technology

High heat dissipation substrates



● TDK's proprietary high heat dissipation substrate and high-performance ferrite material used to achieve size reduction and efficiency improvements

Wireless charging during driving

● Compliance with noise regulations set out in the Radio Law, using TDK's proprietary coil noise reduction technology

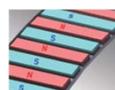
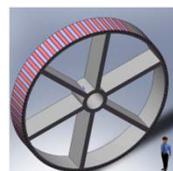


- Strengthen energy devices for renewable energy-related systems
- Promote the sales of power components drawing on magnetic technology, which is TDK's core competence

Industrial equipment & energy fields

1 to 2 years

3 to 5 years



● Free from the impact of instability in the supply of rare-earth elements

Rare-earth-free/strongest magnetic materials for wind power generation

Lead-free piezoelectric materials (thin-film, bulk)

Secondary batteries (Stationary type, high-safety battery technology)

Dy-free magnets with Nd reduced by half for wind power generation

Lead-free piezoelectric material (Ceralink)

● Ceramic capacitors that reach the maximum capacitance under a high DC bias voltage

● Battery material technology combined with processing technology to reduce electrode expansion

High-capacity high-efficiency power supplies

Secondary batteries (Storage battery systems)

● Deployment of wireless charging technology for xEVs in the area of industrial equipment

Wireless charging systems (for industrial machinery)

Chip component moulder



- Build wireless charging systems for use in the automotive and industrial equipment fields

Automotive and industrial equipment fields



Small power-receiving coil unit



- Downsized power-receiving coil with a built-in multilayer ceramic capacitor

High-efficiency 3.3 kW transmission



- High transmission efficiency achieved by using low core loss material PC95
- Vibration resistance rendered by TDK's proprietary ferrite material

Wireless charging systems for xEVs



Forklift/AGV※

- Application of wireless charging technology to forklifts

※Automatic Guided Vehicle

Outdoor cart

- Application of wireless charging technology to outdoor carts



TDK has developed thin-film technologies through its head business and materials technologies through its passive component business. By merging these technologies, we will provide high value-added products that positively respond to the needs of the information and communications fields that are expected diversify in the future.

Advantages of thin-film technology

Reduced conductor shape variability

Reduced variability in film thickness for dielectric materials and piezoelectric layers

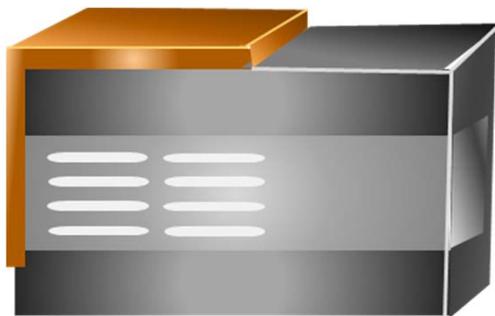
High aspect ratio (conductor)

Differences from semiconductor technology

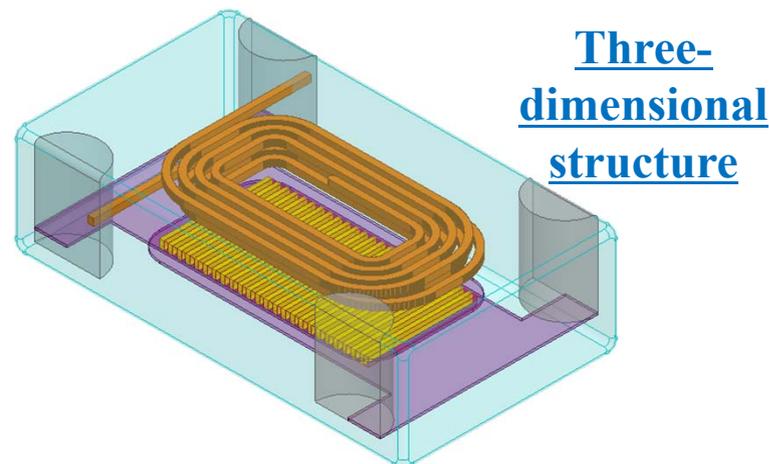
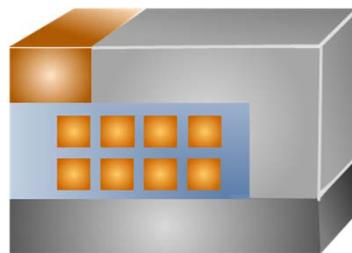
Three-dimensional fine structure

Features of thin-film materials (magnetic/dielectric/piezoelectric) used at the core of TDK's high-performance products

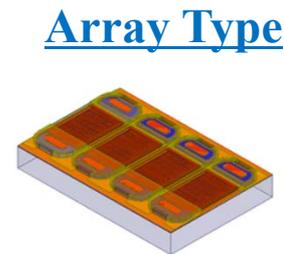
Multilayer type



Thin Film type



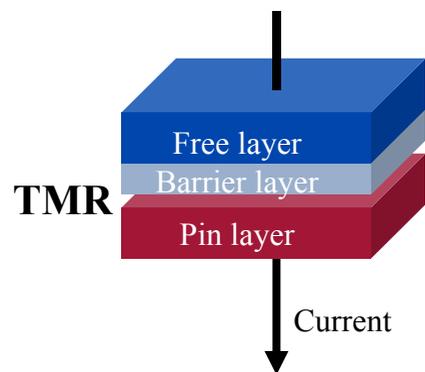
Product family	Feature
Common-mode filters	Size reduction and performance improvements
High-frequency filters	Reduced footprint enabled by size reduction and use of arrayed configuration Performance improvements in high-frequency
Inductors	Low-profile power devices (low-profile modules) and embedded high Q-factor types (low profile)
Composite components (capacitors and inductors)	Reduced footprint and low profile achieved by composite design.
MEMS	Three-dimensional structure and material characteristics used at the core to achieve performance improvements.





Application	Accuracy of predecessor	Future accuracy requirement
Throttle valves	$\pm 2^\circ$ to $\pm 3^\circ$	$\pm 1^\circ$
Wipers	$\pm 1.2^\circ$ (20 to 130 mT)	$\pm 0.6^\circ$ (20 to 130 mT)
Steering (EPS motor)	$\pm 0.6^\circ$ (20 to 80 mT)	$\pm 0.3^\circ$ (20 to 80 mT) Redundancy ISO 26262

At least a two-fold angle sensing accuracy will be realized with this technology

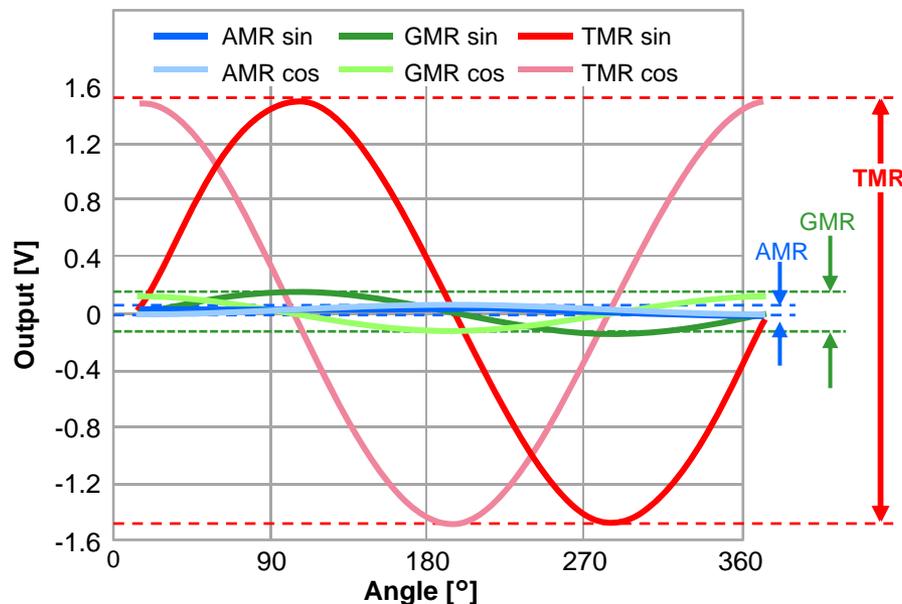


	MR Ratio [%]	Output [mV]	SNR @ 10 kHz [dB]	Temperature dependence 25 °C to 125 °C [%]
AMR	3	90	72	-29
GMR	12	360	77	-23
TMR	100	3000	96	-13

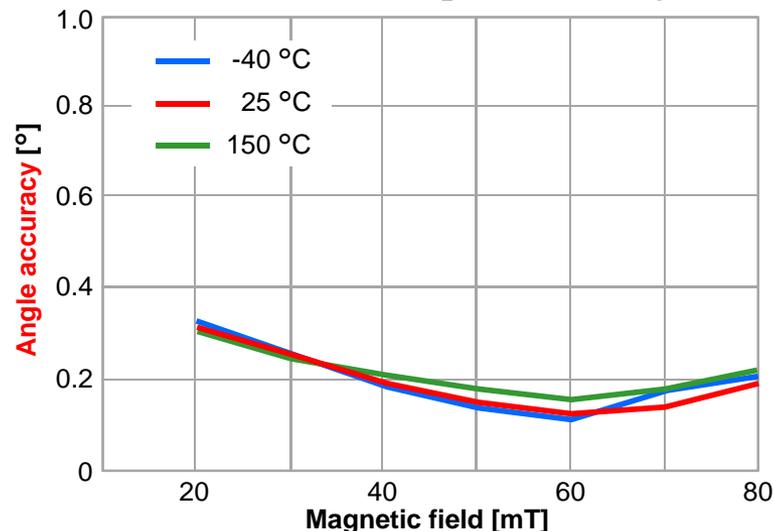
TMR Output

- 30 times better than AMR
- 8 times better than GMR
- Stable angle sensing accuracy across a broad range of temperature variations

Output waveforms

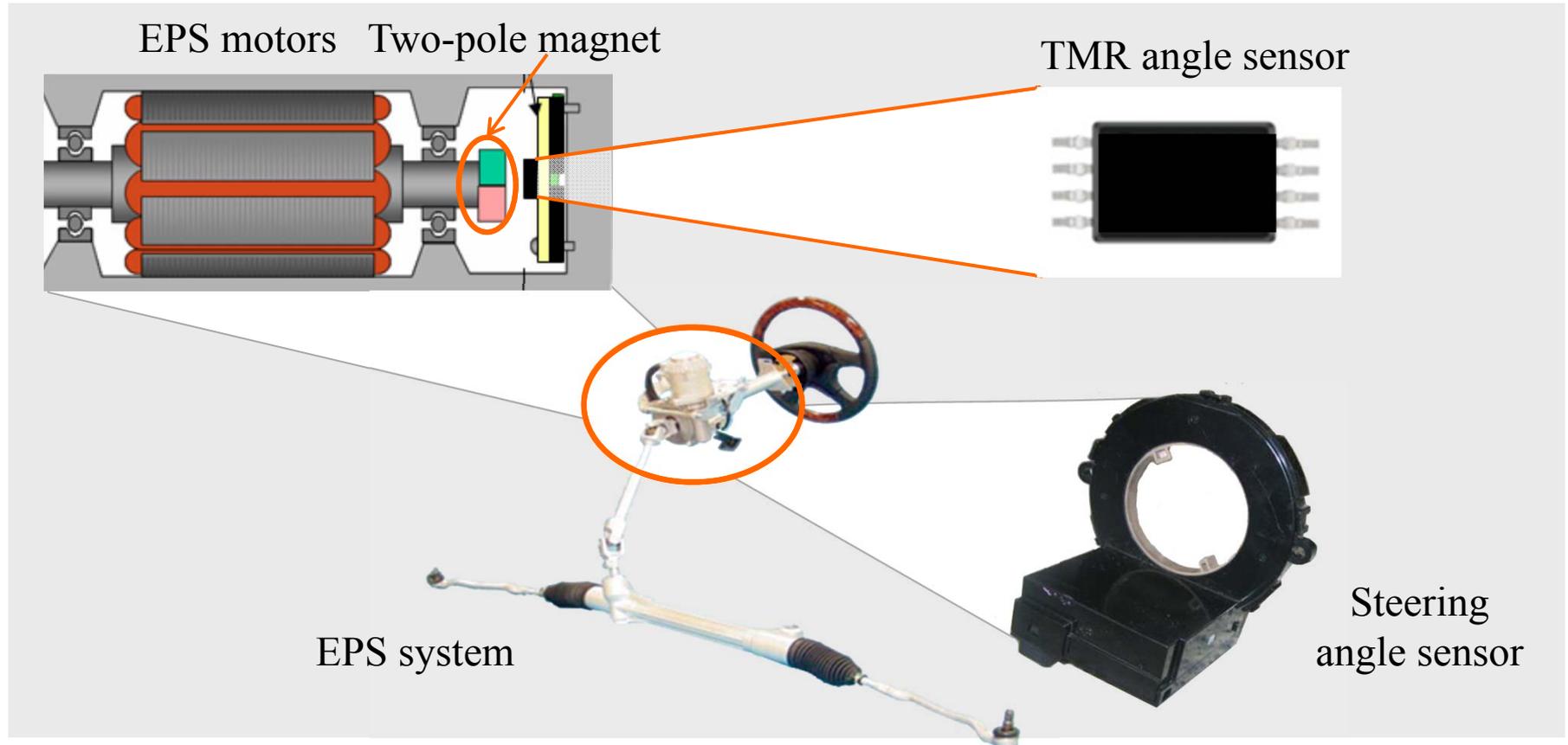


Angle sensing accuracy vs. magnetic field in a broad temperature range



- **High power**
3.0V_{pp} @ 5 V (30x AMR, 8x GMR)
- **Excellent angle sensing accuracy**
Angle sensing error: within $\pm 0.6^\circ$
Conditions : Magnetic field range: 20 to 80 mT / Temperature range: -40°C to 150°C
- **Low power consumption**
5 mW (under recommended conditions)

Steering systems: Largest angle sensor market



TMR sensor opposed to two-pole magnet

TDK TMR sensors : Enhanced product families for our customers



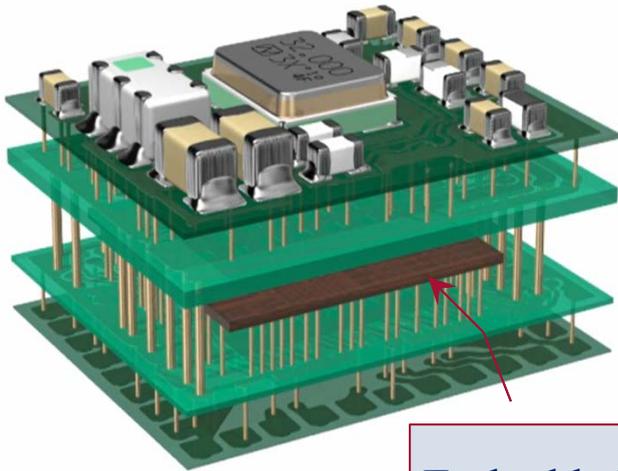
- **High-accuracy angle sensors**
- **Rotation sensors**
- **Linear encoders**
- **Rotary encoders**
- **Current sensors**

Angle sensors and other sensor products are geared to meet diverse application needs

Target applications of thin-film devices/SESUB

Target Applications		SESUB	Thin Film Devices
Smartphones • Tablet Devices	Power line use	Power Module	Low-profile inductors
	RF use	PA/RF Module	High Frequency Filters Capacitors downsized, arrayed and with narrow tolerance High Q inductors MEMS
	Sensor	Asic Package	
	Other		Common mode filters Composite components
Wearable devices (health care)	Power line use	Charger Module	Low-profile inductors
	RF use	PAN Module	
	Sensor	Asic Package	
Data Centers (servers)	CPU		Embedded capacitors

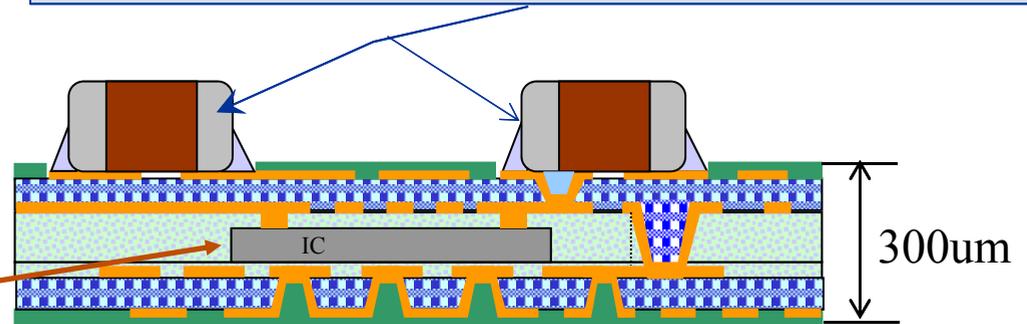
SESUB product features



Embedded IC

SESUB cross-sectional view

Components can be mounted on SESUB as on plastic substrates

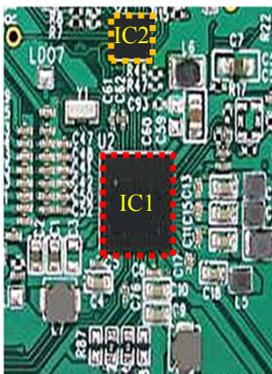


Size reduction

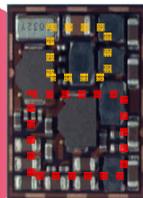
A high percentage of embedded components enables downsizing

Discrete Solution = 350mm²

SESUB Module = 121mm²

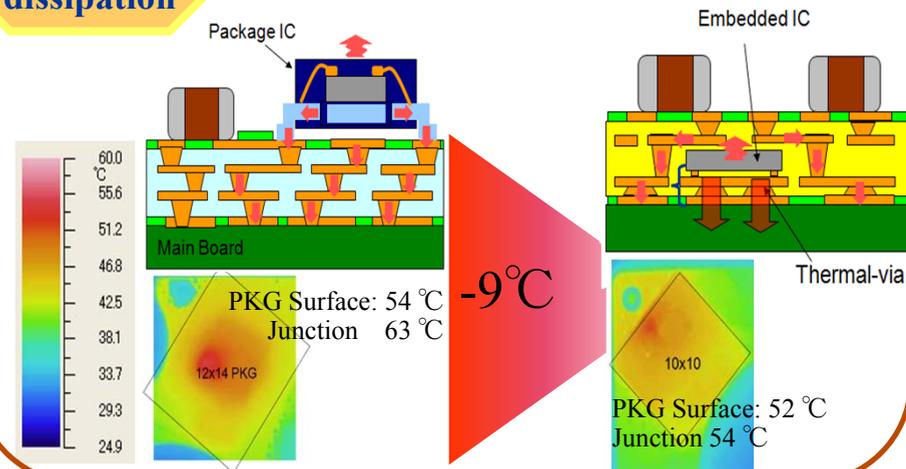


-65%



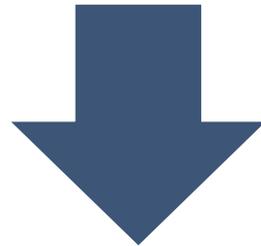
Excellent heat dissipation

Excellent heat dissipation capability
To raise the degree of design freedom



Business model for SESUB products

Market change Industry led by IC manufacturers rather than by telephone manufacturers



- Uniformized specifications
- Standardized OS (e.g., Android and iOS)
- Shortened development period

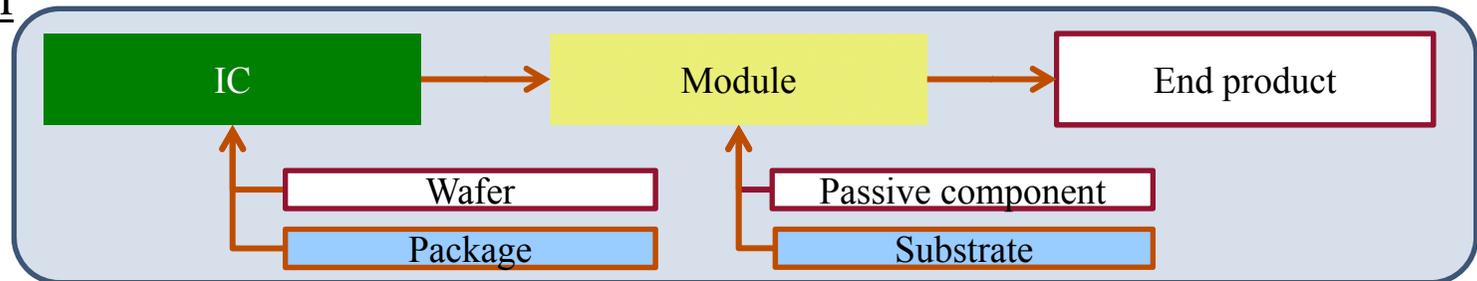


Smartphone manufacturers use IC manufacturers' references

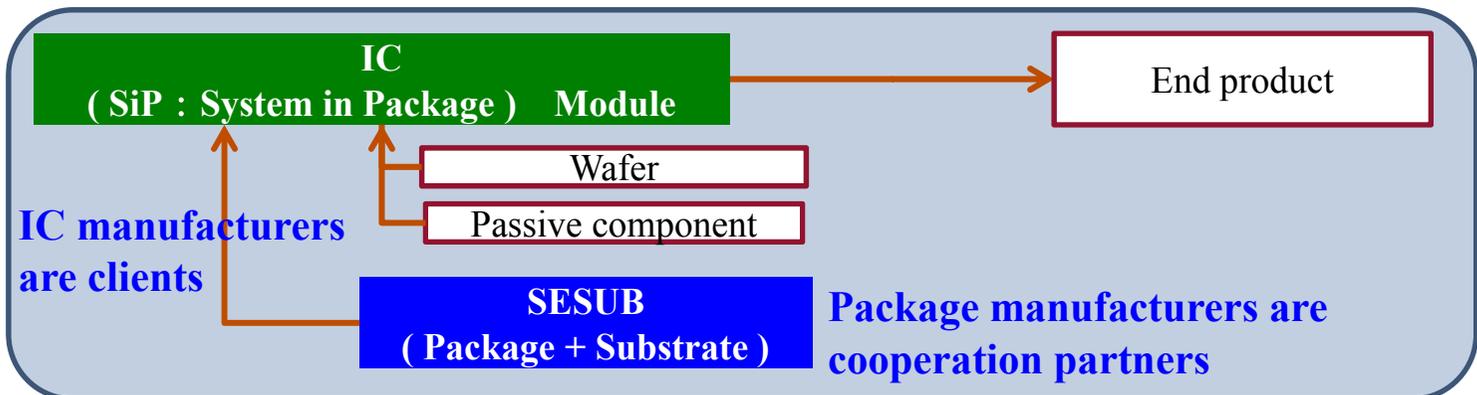
SESUB business: IC manufacturers are our clients, while IC package manufacturers are our cooperation partners

Business model

Conventional model



SESUB



- ① Launch new businesses following the three key segments to hit ¥100 billion sales**
- ② Pursue zero-defect quality drawing on the Company's high level of technical expertise**
- ③ Conduct speedy business operations to promote true globalization**

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